



Changes Rev F IPC-A-610 and IPC J-STD-001F

Two leading standards for the electronics assembly industry have been revised. IPC J-STD-001F, *Requirements for Soldered Electrical and Electronic Assemblies* is recognized worldwide as the sole industry-consensus standard for soldering processes and materials. IPC-A-610F, *Acceptability of Electronic Assemblies*, is a post-assembly acceptance standard used to ensure electronics assemblies meet acceptance requirements.

Some significant changes to both standards include:

- Requirements added for two new SMT terminations
 - P-Style terminations
 - Butt/I terminations — Solder charged terminations
- Revised Class 2 plated-through hole vertical solder fill requirements
- Revised void criteria for BGA/CSP components
- Revised class 2 flux activity criteria
- Improved language for ease of readability and understanding
- Revised soldering requirements for plastic SMT components
- Expanded conformal coating section
- New photos added for clarity
- Simplified Imperial English dimensions utilized in the documents
- Explicit to IPC J-STD-001, revised appendices including guidelines for soldering tools and equipment and objective evidence on material compatibility